



## News Release

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FOR IMMEDIATE RELEASE

### **COMIT Interface Standard Makes Next Generation Computer-on-Module Products Easier to Use, More Reliable**

*Single connector interface includes PCI Express, USB and More*

San Jose, CA, March 30, 2009 - The Small Form Factor Special Interest Group (SFF-SIG) a collaboration of suppliers of embedded component, board and system technologies, today announced COMIT, a new form-factor independent, Computer-on-Module interface standard. COMIT stands for Computer On Module Interconnect Technology™ and is targeted towards small form factor COM processor modules and host baseboards leveraging the latest ultra-mobile and low power processor/chipset combinations. COMIT is the enabling technology to allow design of tiny processor modules to fit within the footprint of industry-standard, small form factor boards such as EBX, EPIC, PC/104, Pico ITX or other standard or custom-designed baseboards.

COMIT is an electromechanical interface specification that is designed to be processor independent and focuses on bus interconnect and module manufacturing technology rather than any single processor, DSP, or microcontroller architecture. COMIT can be used to support different processors with a single baseboard allowing easy migration to future processors for performance/feature enhancement or for obsolescence mitigation. The purpose is to enable compact, easy-to-use, reliable COM solutions for embedded systems designs suitable for industrial environments using the newest low power chip sets.

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In a single 6 x 40 connector, COMIT's 240 pins supports three PCI Express™ x1 lanes, one PCI Express x4 lane, six high-speed USB 2.0 channels, VGA, SDVO, and dual LVDS video interfaces, two SATA channels, Ethernet, 8-bit SDIO, HD Audio, LPC (Low Pin Count) Bus, SPI/uWire, SMBus/I<sup>2</sup>C Bus, system clock and control signaling plus ample power and ground. The use of a single connector eliminates registration problems that plagued manufacturing with products based on earlier generation COM standards.

COMIT uses the SEARAY™ high speed, high pin density, rugged, and low cost connector system from Samtec. It is a second-sourced, compact, and rugged connector well suited for both commercial and industrial applications for current and future embedded systems designs. SEARAY is capable of differential signaling rates of 9 GHz bandwidth which can support interfaces like PCI Express Gen2 and USB3. These extremely rugged connectors are also some of the lowest cost-per-pin and highest density available on the market for this type of multi-gigahertz capable interconnect.

“With the advent of the latest low-power, high-integration ATOM™ and Nano™ x86 processors and chipsets from Intel and VIA, plus the special manufacturing issues associated with high ball count micro BGAs and new high-speed serial interfaces, there are significant technology problems faced by SBC designers to cost effectively integrate these technologies,” said Paul Rosenfeld, SFF-SIG President. “The COMIT Standard utilizes the latest connector technology and manufacturing techniques to address these complex issues creating cost-effective solutions offering quick time-to-market.”

Companies interested in participating in the future evolution of COMIT or other small form factor definitions should contact the SFF-SIG at [info@sff-sig.org](mailto:info@sff-sig.org).

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## **About the Small Form Factor Special Interest Group**

The Small Form Factor Special Interest Group is an international organization devoted to identifying, creating, and promoting standards that help electronics system and device manufacturers and integrators move to small form factor technologies and building blocks in their products, and protect their investments. Benefits of small form factor products include smaller size, reduced power consumption (eco-friendly, “green” products), and greater reliability compared to larger legacy products.

The SIG’s philosophy is to embrace the latest technologies and maintain legacy compatibility to enable smooth transition solutions for next-generation processor and I/O interfaces. For more information about the SFF SIG, please visit [www.sff-sig.org](http://www.sff-sig.org) or e-mail [info@sff-sig.org](mailto:info@sff-sig.org).

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